

RoHS

COMPLIANT

FDA79N15-VB Datasheet

N-Channel 150V (D-S) MOSFET

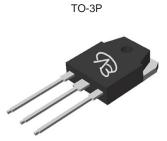
PRODUCT SUMMARY			
V _{(BR)DSS} (V)	r _{DS(on)} (Ω)	I _D (A)	
150	0.017 at V _{GS} = 10 V	90 ^a	

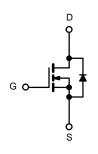
FEATURES

- Trench Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested

APPLICATIONS

• Isolated DC/DC Converters





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted			
Parameter	-	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	150	v	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current ($T_1 = 175 ^{\circ}C$)	T _C = 25 °C	1-	90 ^a		
Continuous Drain Current $(T_J = 175^{\circ}C)$	T _C = 125 °C	I _D	75 ^a	A	
Pulsed Drain Current		I _{DM}	250	~	
Avalanche Current	L = 0.1 mH	I _{AS}	35		
Single Pulse Avalanche Energy ^b	L = 0.1 mm	E _{AS}	61	mJ	
	T _C = 25 °C	P	375 ^c	14/	
Maximum Power Dissipation ^b	T _A = 25 °C ^d	– P _D –	3.75	- W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W
Junction-to-Case (Drain)		R _{thJC}	0.4	C/VV

Notes:

a. Package limited.

b. Duty cycle \leq 1 %.

c. See SOA curve for voltage derating.

d. When Mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS $T_J = 25 \circ 0$	C, unless o						
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	1			1	1	1	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	150			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		4	•	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 100 V, V_{GS} = 0 V, T_{J} = 125 °C			50	μΑ	
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	120			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$		0.017			
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.023		Ω	
		V_{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.034			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	•			•	•	•	
Input Capacitance	C _{iss}			5100		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz$		480			
Reverse Transfer Capacitance	C _{rss}			210			
Total Gate Charge ^c	Qg			90	130		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 100 V, V_{GS} = 10 V, I_{D} = 65 A		23		nC	
Gate-Drain Charge ^c	Q _{gd}			34			
Gate Resistance	Rg		0.5	1.7	3.3	Ω	
Turn-On Delay Time ^c	t _{d(on)}			24	35		
Rise Time ^c	t _r	V_{DD} = 100 V, R _L = 1.5 Ω		220	330	ns	
Turn-Off Delay Time ^c	t _{d(off)}	${ m I}_{ m D}\cong$ 65 A, ${ m V}_{ m GEN}$ = 10 V, ${ m R}_{ m g}$ = 2.5 Ω		45	70		
Fall Time ^c	t _f			200	300		
Source-Drain Diode Ratings and Cha	racteristics 7	$\Gamma_{\rm C} = 25 \ ^{\circ}{\rm C}^{\rm b}$					
Continuous Current	ا _S				65	А	
Pulsed Current	I _{SM}				140	A	
Forward Voltage ^a	V _{SD}	I _F = 65 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			130	200	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, di/dt = 100 A/µs		8	12	А	
Reverse Recovery Charge	Q _{rr}			0.52	1.2	μC	

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

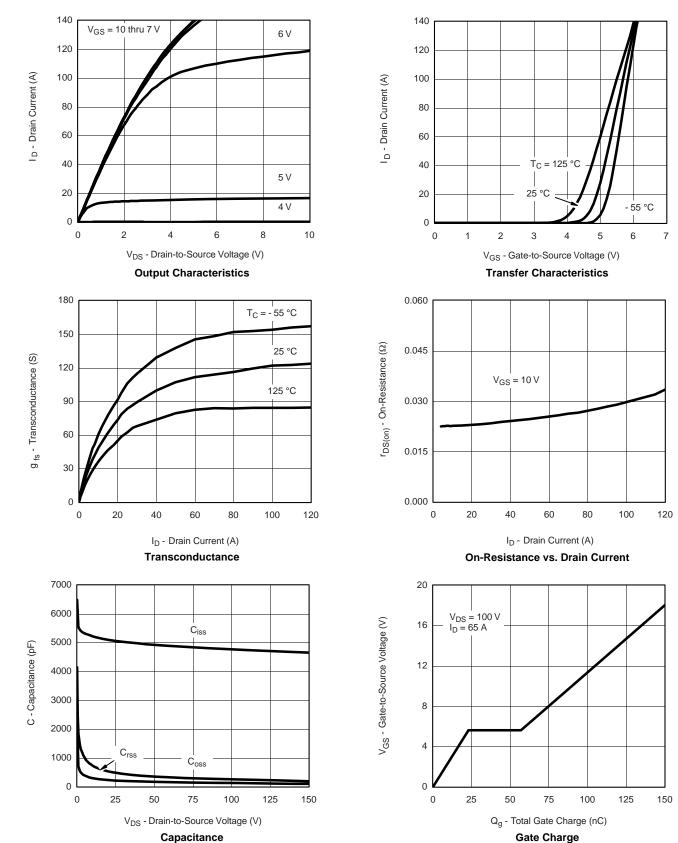
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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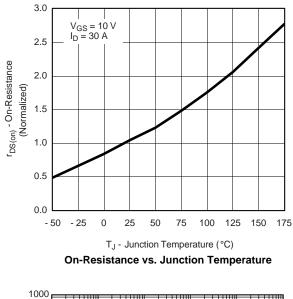


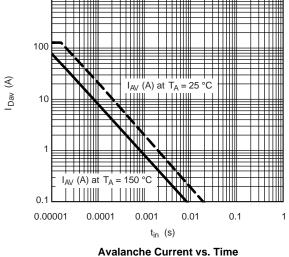


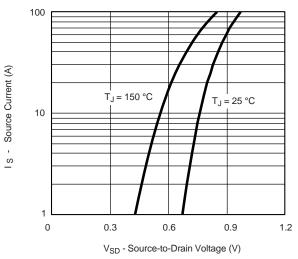
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



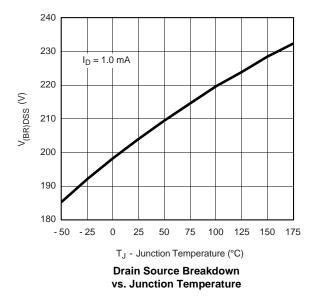
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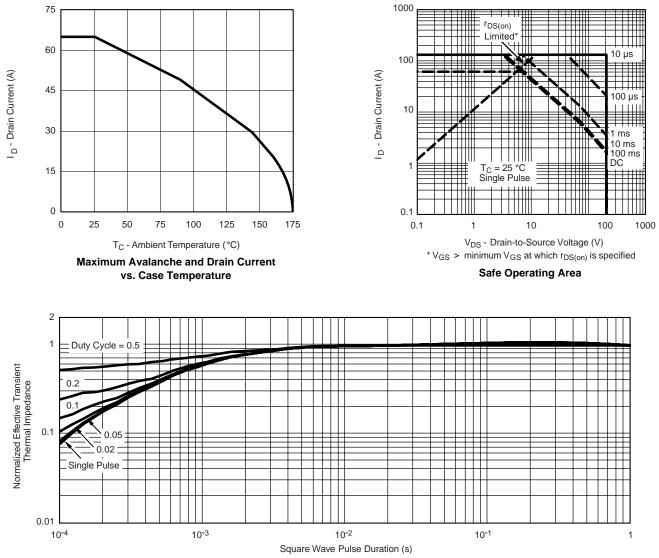


Source-Drain Diode Forward Voltage



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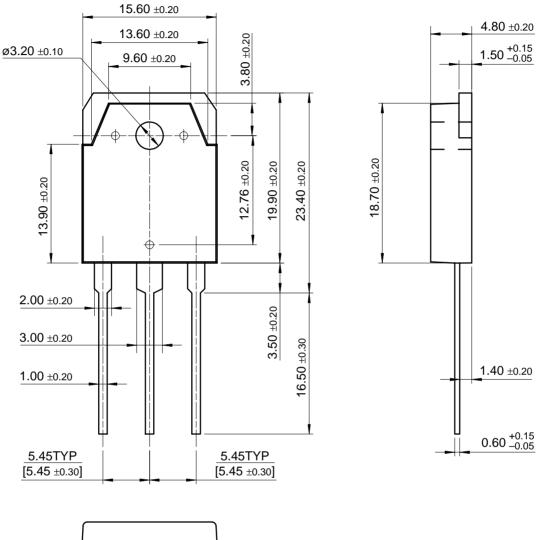
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-3P



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